

MOS FIELD EFFECT TRANSISTOR 2SK2411, 2SK2411-Z

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

DESCRIPTION

The 2SK2411 is N-Channel MOS Field Effect Transistor designed for high speed switching applications.

FEATURES

- Low On-Resistance
 $R_{DS(on)1} = 40 \text{ m}\Omega \text{ MAX. (@ } V_{GS} = 10 \text{ V, } I_D = 15 \text{ A)}$
 $R_{DS(on)2} = 60 \text{ m}\Omega \text{ MAX. (@ } V_{GS} = 4 \text{ V, } I_D = 15 \text{ A)}$
- Low C_{iss} $C_{iss} = 1500 \text{ pF TYP.}$
- Built-in G-S Gate Protection Diodes
- High Avalanche Capability Ratings

QUALITY GRADE

Standard

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

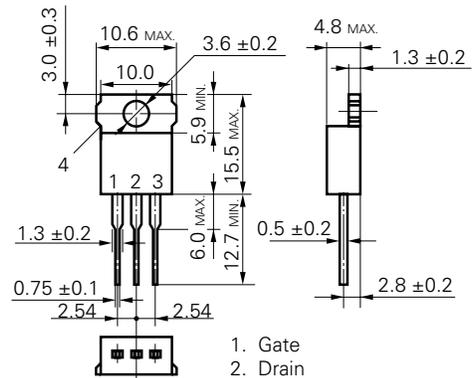
ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

| | | | |
|--|----------------|-------------|------------------|
| Drain to Source Voltage | V_{DSS} | 60 | V |
| Gate to Source Voltage | V_{GSS} | ± 20 | V |
| Drain Current (DC) | $I_{D(DC)}$ | ± 30 | A |
| Drain Current (pulse)* | $I_{D(pulse)}$ | ± 120 | A |
| Total Power Dissipation ($T_c = 25^\circ\text{C}$) | P_{T1} | 75 | W |
| Total Power Dissipation ($T_A = 25^\circ\text{C}$) | P_{T2} | 1.5 | W |
| Channel Temperature | T_{ch} | 150 | $^\circ\text{C}$ |
| Storage Temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ |
| Single Avalanche Current** | I_{AS} | 30 | A |
| Single Avalanche Energy** | E_{AS} | 90 | mJ |

* $PW \leq 10 \mu\text{s}$, Duty Cycle $\leq 1\%$

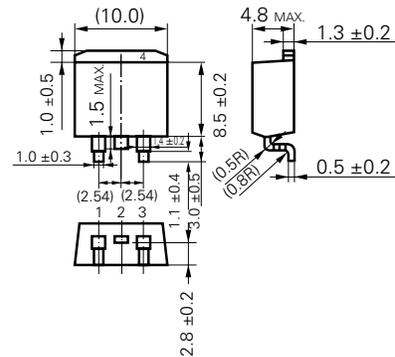
** Starting $T_{ch} = 25^\circ\text{C}$, $R_G = 25 \Omega$, $V_{GS} = 20 \text{ V} \rightarrow 0$

PACKAGE DIMENSIONS (in millimeter)

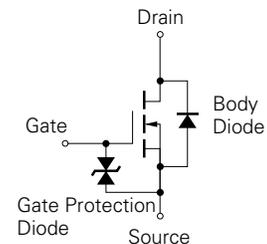


1. Gate
 2. Drain
 3. Source
 4. Fin (Drain)
- JEDEC: TO-220AB

MP-25 (TO-220)



MP-25Z (SURFACE MOUNT TYPE)

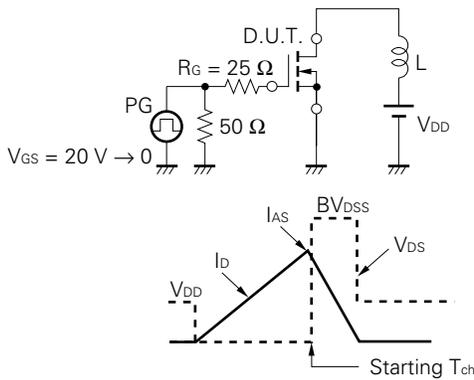


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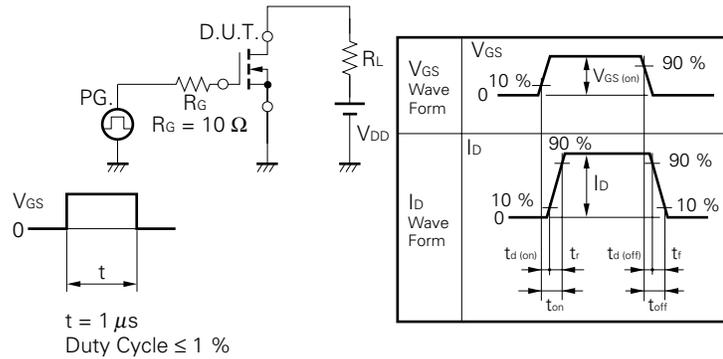
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

| CHARACTERISTIC | SYMBOL | MIN. | TYP. | MAX. | UNIT | TEST CONDITIONS |
|--------------------------------|----------------------|------|------|------|------|---|
| Drain to Source On-Resistance | R _{DS(on)1} | | 31 | 40 | mΩ | V _{GS} = 10 V, I _D = 15 A |
| Drain to Source On-Resistance | R _{DS(on)2} | | 40 | 60 | mΩ | V _{GS} = 4 V, I _D = 15 A |
| Gate to Source Cutoff Voltage | V _{GS(off)} | 1.0 | 1.5 | 2.0 | V | V _{DS} = 10 V, I _D = 1 mA |
| Forward Transfer Admittance | y _{fs} | 15 | 27 | | S | V _{DS} = 10 V, I _D = 15 A |
| Drain Leakage Current | I _{bss} | | | 10 | μA | V _{DS} = 60 V, V _{GS} = 0 |
| Gate to Source Leakage Current | I _{GSS} | | | ±10 | μA | V _{GS} = ±20 V, V _{DS} = 0 |
| Input Capacitance | C _{iss} | | 1500 | | pF | V _{DS} = 10 V |
| Output Capacitance | C _{oss} | | 720 | | pF | V _{GS} = 0 |
| Reverse Transfer Capacitance | C _{rss} | | 190 | | pF | f = 1 MHz |
| Turn-On Delay Time | t _{d(on)} | | 20 | | ns | I _D = 15 A |
| Rise Time | t _r | | 260 | | ns | V _{GS(on)} = 10 V |
| Turn-Off Delay Time | t _{d(off)} | | 130 | | ns | V _{DD} = 30 V |
| Fall Time | t _f | | 150 | | ns | R _G = 10 Ω |
| Total Gate Charge | Q _G | | 50 | | nC | I _D = 30 A |
| Gate to Source Charge | Q _{GS} | | 5.0 | | nC | V _{DD} = 48 V |
| Gate to Drain Charge | Q _{GD} | | 15 | | nC | V _{GS} = 10 V |
| Body Diode Forward Voltage | V _{F(S-D)} | | 1.1 | | V | I _F = 30 A, V _{GS} = 0 |
| Reverse Recovery Time | t _{rr} | | 110 | | ns | I _F = 30 A, V _{GS} = 0 |
| Reverse Recovery Charge | Q _{rr} | | 320 | | nC | di/dt = 100 A/μs |

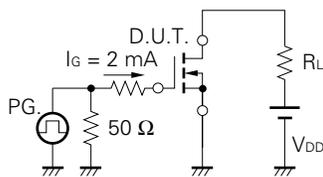
Test Circuit 1 Avalanche Capability



Test Circuit 2 Switching Time



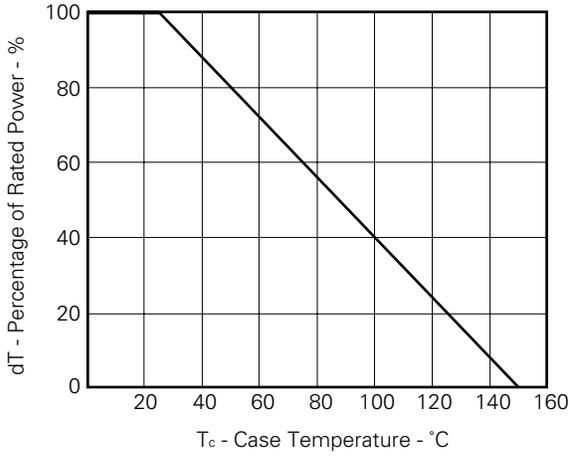
Test Circuit 3 Gate Charge



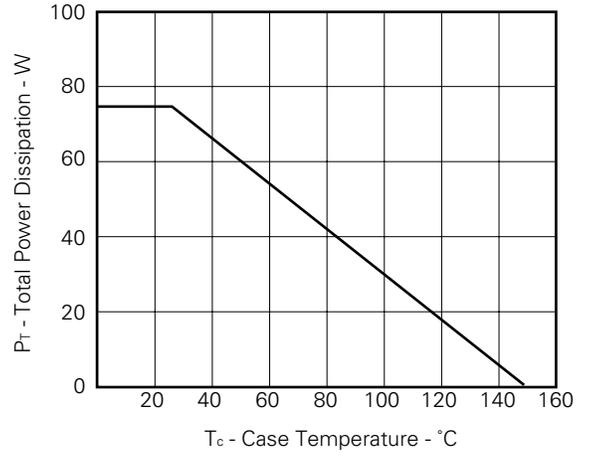
The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

TYPICAL CHARACTERISTICS (T_A = 25 °C)

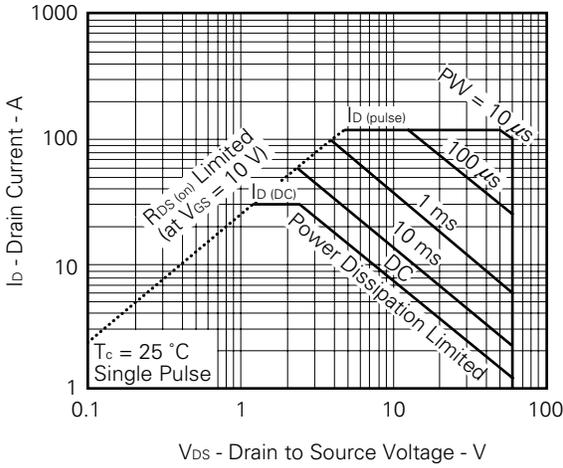
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



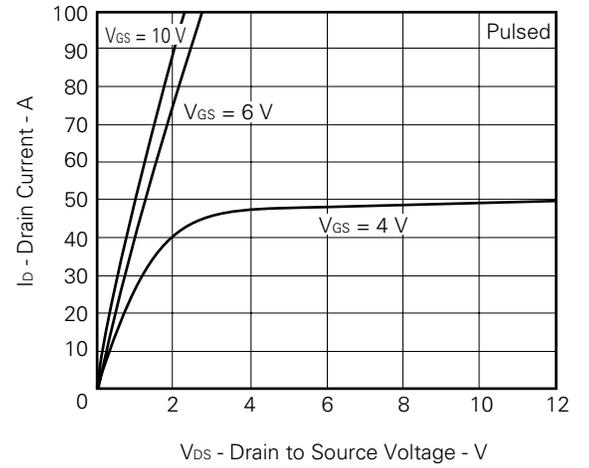
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



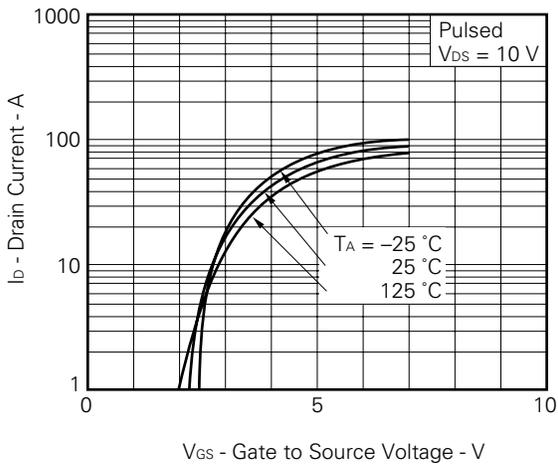
FORWARD BIAS SAFE OPERATING AREA



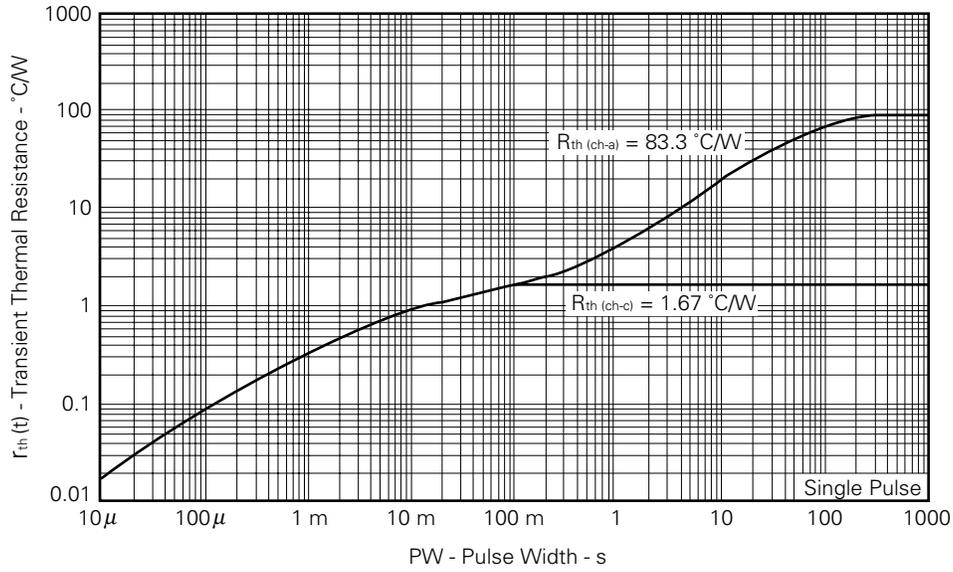
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



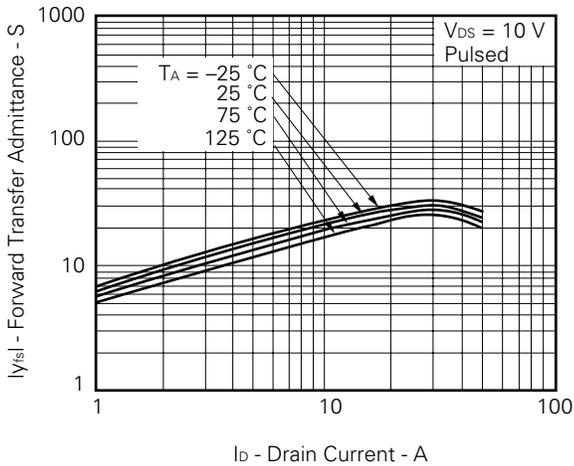
FORWARD TRANSFER CHARACTERISTICS



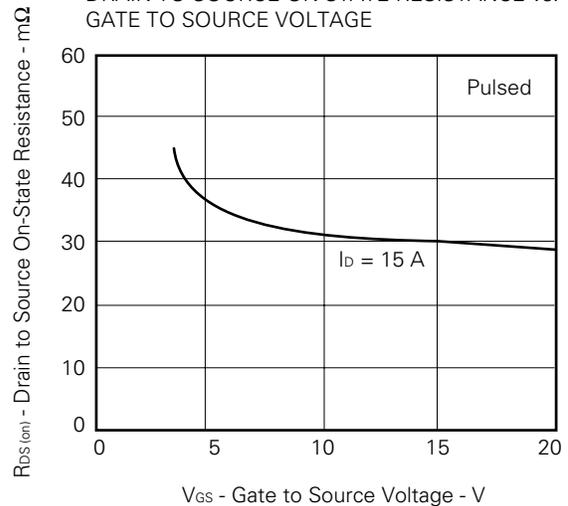
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



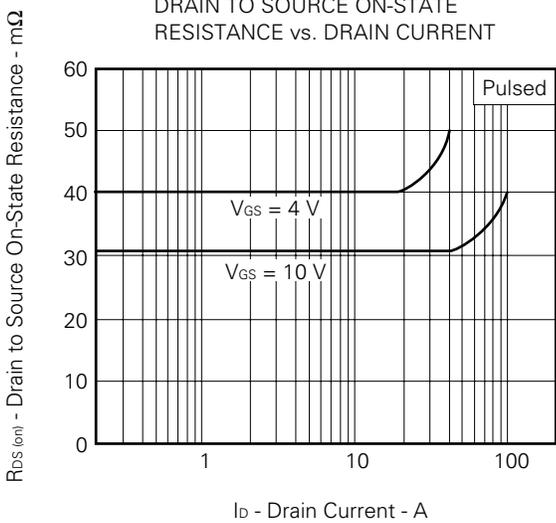
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



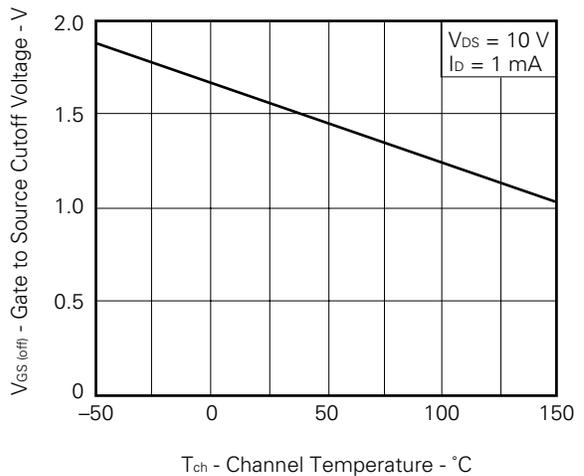
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

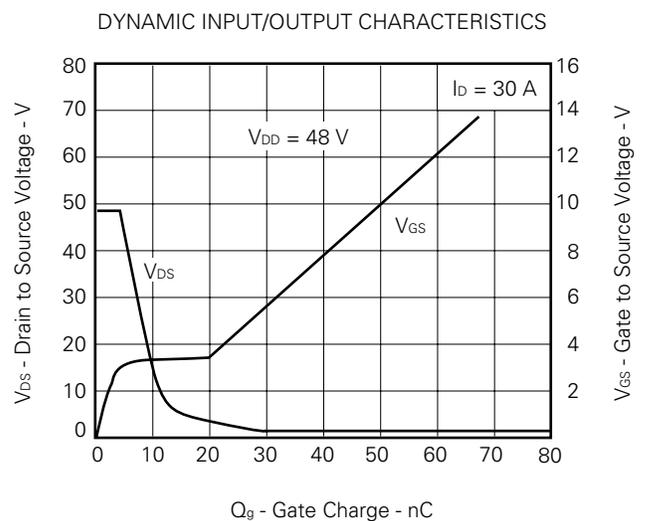
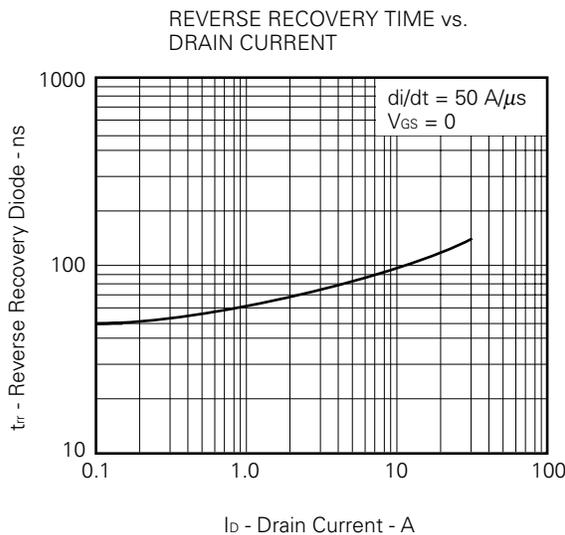
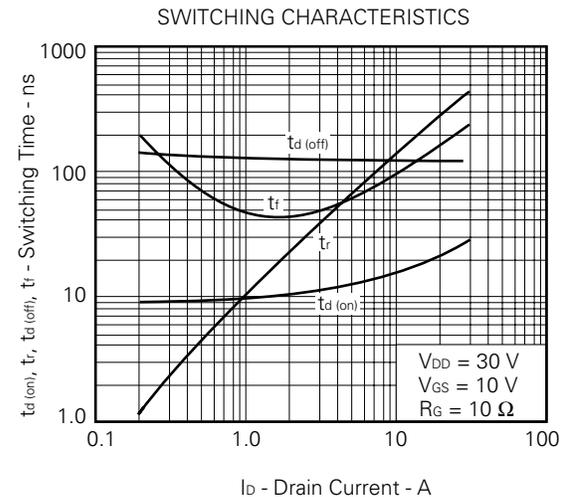
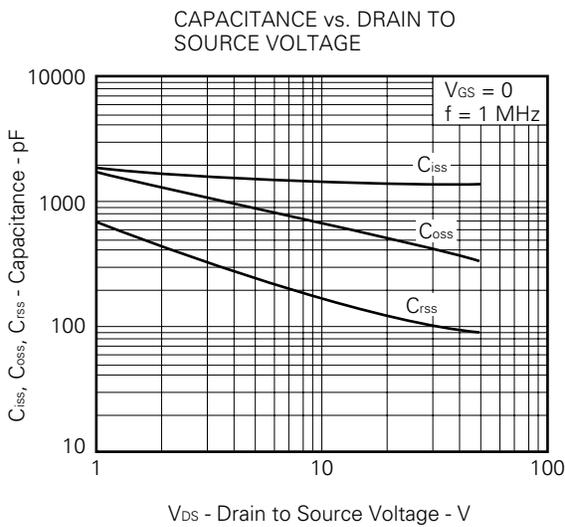
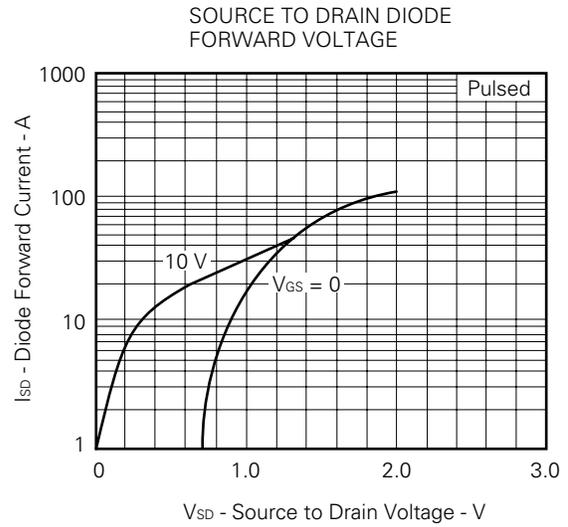
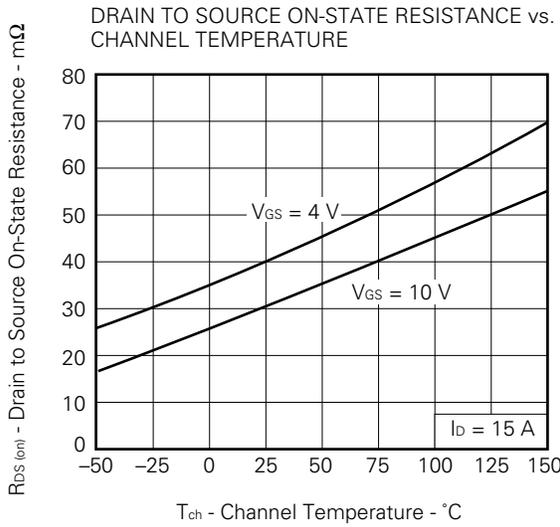


DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

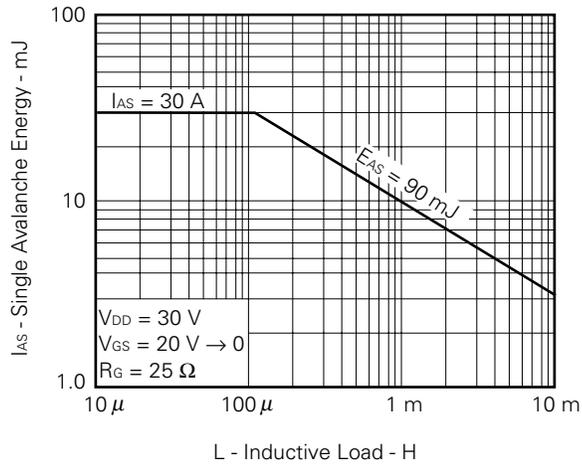


GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE

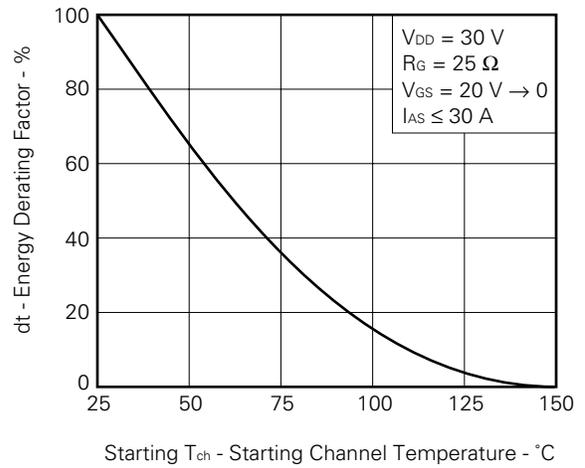




SINGLE AVALANCHE ENERGY vs. INDUCTIVE LOAD



SINGLE AVALANCHE ENERGY DERATING FACTOR



REFERENCE

| Document Name | Document No. |
|--|--------------|
| NEC semiconductor device reliability/quality control system. | TEI-1202 |
| Quality grade on NEC semiconductor devices. | IEI-1209 |
| Semiconductor device mounting technology manual. | IEI-1207 |
| Semiconductor device package manual. | IEI-1213 |
| Guide to quality assurance for semiconductor devices. | MEI-1202 |
| Semiconductor selection guide. | MF-1134 |
| Power MOS FET features and application switching power supply. | TEA-1034 |
| Application circuits using Power MOS FET. | TEA-1035 |
| Safe operating area of Power MOS FET. | TEA-1037 |

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device is actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

[MEMO]

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Application examples recommended by NEC Corporation

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Special: Automotive and Transportation equipment, Traffic control systems, Antidisaster systems, Anticrime systems, etc.